AB354NT

Photocoupler

FEATURES

- AC inputs
- High current transfer ratio
- Opaque type, mini-flat package
- Subminiature type (The volume is smaller than that of our conventional DIP type by as far as 30%)
- Maximum working isolation voltage V_{IOWM} = 450 V_{RMS}
- Maximum repetitive peak isolation voltage V_{IORM} = 630 V_{peak}
- Maximum transient isolation voltage V_{IOTM} = 6 kV_{peak}
- Maximum withstanding isolation voltage V_{ISO} = 3750 V_{RMS}
- Employs double transfer mold technology
- Recognized by UL and CUL, file NO.E225308
- Package: 1000 pcs/reel
- Moisture sensitivity level : 4
- RoHS compliant

APPLICATIONS

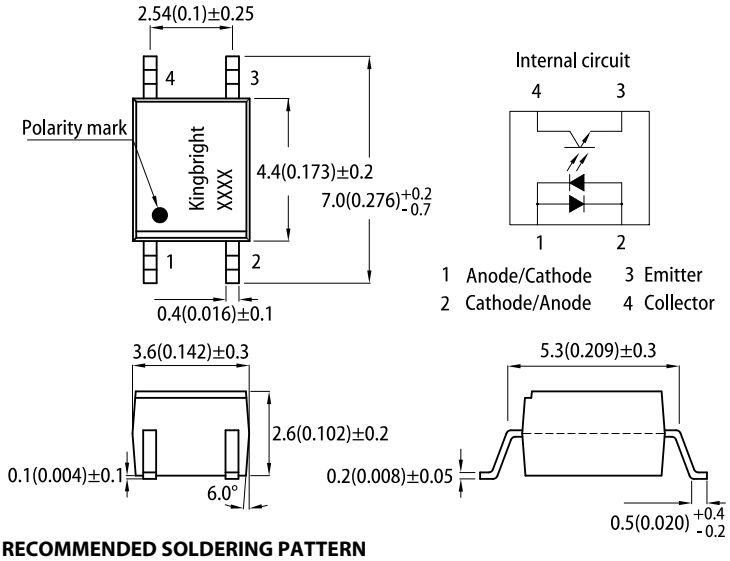
- Hybrid substrates that require high density mounting
- Programmable controllers

NOTES ON HANDLING

Cautions regarding electrical noise

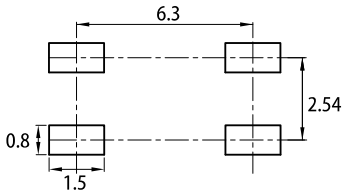
Please ensure the power supply is stable at all times. Even if the designed operating voltage is within specification limits, sudden voltage spikes at startup may damage the component.

PACKAGE DIMENSIONS



RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.15)



Notes:
1. *All dimensions are in millimeters (inches).*
2. *Tolerance is ±0.5(0.02") unless otherwise noted.*
3. *The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.*
4. *The device has a single mounting surface. The device must be mounted according to the specifications.*

ELECTRICAL / OPTICAL CHARACTERISTICS at T_A=25°C

Parameter			Symbol	Value			Unit	Test Conditions
				Min.	Typ.	Max.		
Input	Forward Voltage		V_F	-	1.2	1.4	V	I_F=±20mA
	Peak Forward Voltage		V_{FM}	-	-	3.0	V	I_{FM}=0.5A
Output	Collector Dark Current		I_{CEO}	-	-	10^{-7}	A	I_F=0mA,V_{CE}=20V
	Collector-Emitter Breakdown Voltage		BV_{CEO}	35	-	-	V	I_F=0mA,I_C=0.1mA
	Emitter-Collector Breakdown Voltage		BV_{ECO}	6	-	-	V	I_F=0mA,I_E=10μA
Transfer Characteristics	Current Transfer Ratio		CTR	20	-	300	%	I_F=±1mA,V_{CE}=5V
	Collector-Emitter Saturation Voltage		$V_{CE(sat)}$	-	0.1	0.2	V	I_F=±20mA,I_C=1mA
	Response Time	Rise Time	t_r	-	4	18	μs	V_{CE}=2V, I_C=2mA R_L=100 Ω
		Fall Time	t_f	-	3	18	μs	

Note:
1. *Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.*

ABSOLUTE MAXIMUM RATINGS at T_A=25°C

Parameter		Symbol	Rating	Unit
Input	Forward Current	I_F	±50	mA
	Power Dissipation	P_D	70	mW
Output	Collector-Emitter Voltage	V_{CEO}	35	V
	Emitter-Collector Voltage	V_{ECO}	6	V
	Collector Current	I_C	50	mA
	Collector Power Dissipation	P_C	150	mW
Total Power Dissipation		P_{tot}	170	mW
Isolation Voltage [1]		V_{iso}	3750	Vrms
Operating Temperature		T_{opr}	-30~+100	°C
Storage Temperature		T_{stg}	-40~+125	°C

Notes:
1.40 to 60% RH,AC for 1 minute.
2.Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

Rank Mark	CTR(%)
L	20 ~ 50
A	50 ~ 150
B	150 ~ 300

MAXIMUM SAFETY RATINGS

Parameter	Symbol	Value			Unit	Test Condition
		Min.	Typ.	Max.		
Input Current	I_{SI}	-	-	200	mA	-
Output Power Dissipation	P_{SO}	-	-	300	mW	-
Ambient Safety Temperature	T_S	-	-	150	°C	-

Note:
1.This optocoupler is designed for electrical isolation only when operating within its specified safety ratings. Compliance with these ratings must be guaranteed by implementing appropriate protective circuits.

TECHNICAL DATA

Fig. 1 Current Transfer Ratio vs. Forward Current

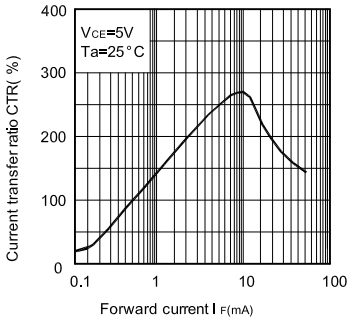


Fig. 2 Forward Current vs. Forward Voltage

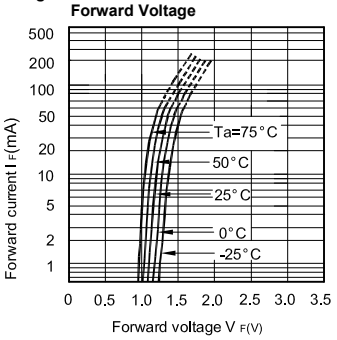


Fig. 3 Collector Current vs. Collector-Emitter Voltage

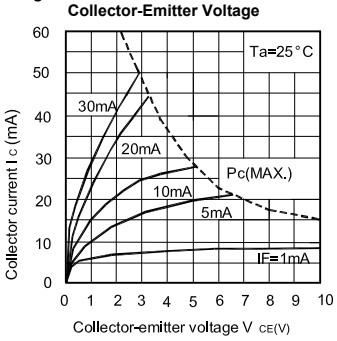


Fig. 4 Relative Current Transfer Ratio vs. Ambient Temperature

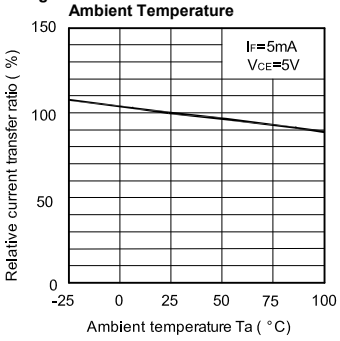


Fig. 5 Collector-Emitter Saturation Voltage vs. Ambient Temperature

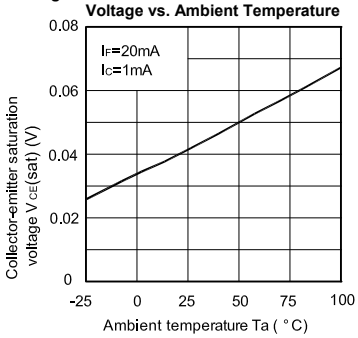


Fig. 6 Response Time vs. Load Resistance

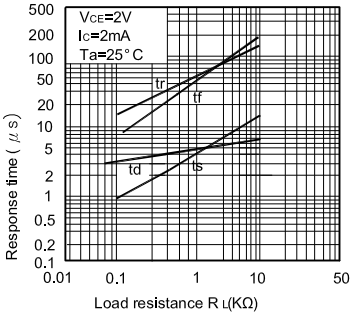


Fig. 7 Collector-Emitter Saturation Voltage vs. Forward Current

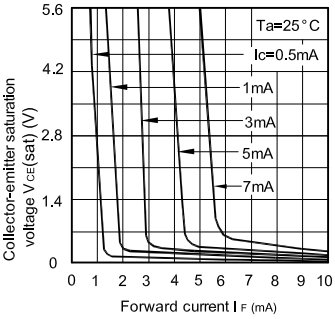
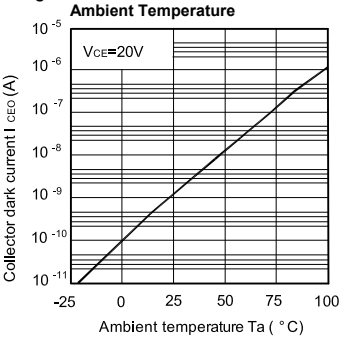
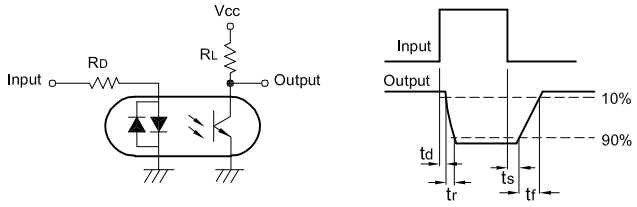


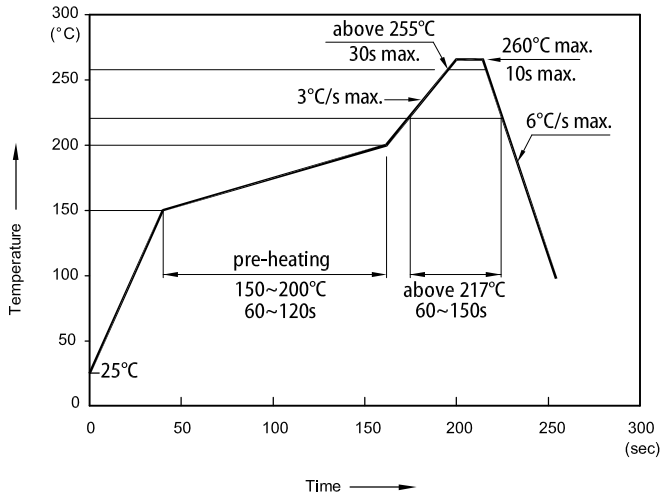
Fig. 8 Collector Dark Current vs. Ambient Temperature



Test Circuit for Response Time

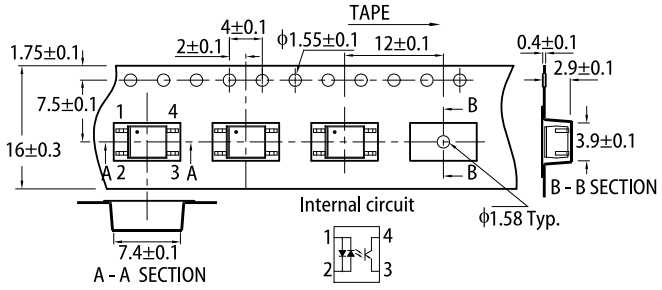


REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

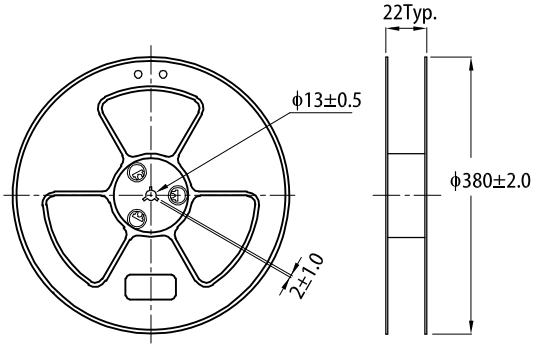


Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
2. The maximum number of reflow soldering passes is 2 times.
3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

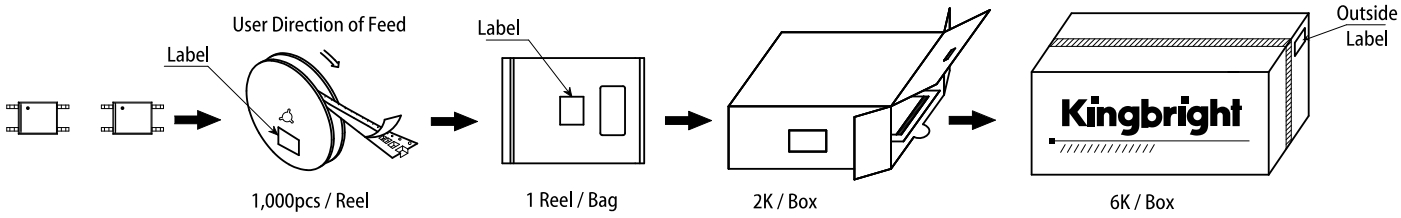
TAPE SPECIFICATIONS (units : mm)

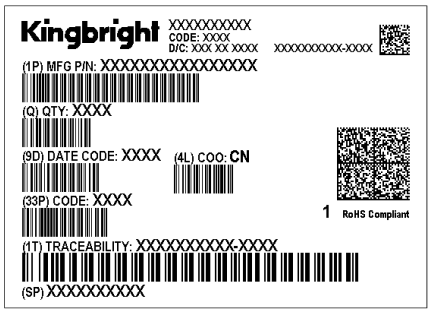


REEL DIMENSION (units : mm)



PACKING & LABEL SPECIFICATIONS





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